

GaN on Si HEMT Process Transfer and Qualification

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Abstract

Nitronex pioneered AlGaIn/GaN HEMTs on commercially available 100mm high resistivity Silicon substrates. Since demonstrating the reliability of these Nitronex NRF1 HEMTs in 2006, well over 500,000 units have been shipped worldwide to top tier customers. Nitronex has further advanced the manufacturability of HEMTs by successfully transferring the wafer fabrication process to Global Communication Semiconductors, Inc. (GCS). This move increases operational excellence in manufacturability for Nitronex products, utilizing GCS' strengths as a pure-play foundry with state-of-art dual thread process platform. This paper will discuss the detailed plans and rapid process transfer execution between these two fabs and the resultant qualification studies.

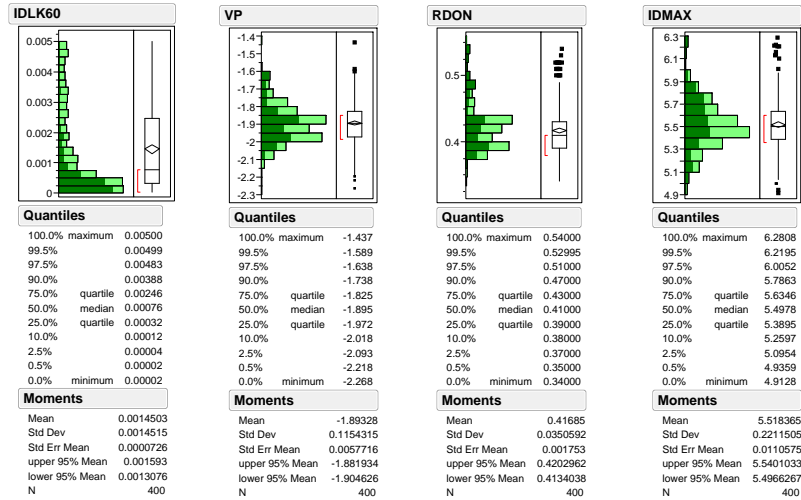
The AlGaIn/GaN high electron mobility transistor (HEMT) is ideal for RF high power applications because of its high power density. The power density is a result of the ability to operate at high voltage combined with high channel current and this power density enables smaller and lighter very wideband power amplifiers with high system efficiency.

The NRF1 process is comprised of the following unit process modules; ohmic contact, isolation, gate formation, passivation, interconnects and backside processing. The process typically produces a contact resistance of <0.4ohm-mm, a channel sheet resistance of 490ohm/square, peak transconductance of 290mS/mm, maximum channel current of 830mA/mm, and drain-gate breakdown voltage of >100V (inline PCM testing), and RF loadpull measurements of 3.9w/mm saturated power and maximum drain efficiency of 57% at 28V and 2.14GHz (inline PCM testing).

Core team members developed a three tier transfer strategy comprised of process module development, integration and qualification. A flexible transfer philosophy was adopted by the team: Copy Nitronex key process modules and re-use GCS existing processes for others when possible. This philosophy added new risks over copy exact, requiring additional process development. However, benefits of this philosophy included the use of more advanced equipment and materials as well as reduced time and expense of procuring and integrating new equipment. Execution of the transfer strategy required a total of 8 integration and qualification lots. The data below is a comparative analysis of DC and RF device performance.

DC Measurements

Dark Green GCS – Light Green Nitronex



RF Measurements

Dark Green GCS – Light Green Nitronex

